

RING (DE)MODULATOR FOR TELEPHONY AND INDUSTRIAL EQUIPMENT

The TBA673 is a monolithic integrated circuit comprising a 4-transistor modulator and demodulator circuit.

The four transistors must be as identical as possible; the lay-out has been designed to achieve this and the best possible tracking of the transistor parameters with temperature.

QUICK REFERENCE DATA

Collector cut-off current

$I_E = 0$; $V_{CB} = 5$ V; $T_{amb} = 25$ °C

$|I_{CBO}| < 100$ nA

Base-emitter voltage differences
between transistors 1, 2, 3, 4

$|V_{BE1}-V_{BE2}| < 5$ mV

$V_{CB} = 5$ V; $-I_E = 150$ µA

$|V_{BE3}-V_{BE4}| < 5$ mV

D.C. current gain differences
between transistors 1, 2, 3, 4

$|\beta_{FB1}-\beta_{FB2}| < 0,008$

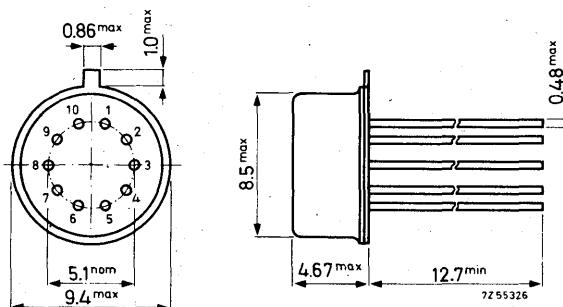
$V_{CB} = 5$ V; $-I_E = 150$ µA

$|\beta_{FB3}-\beta_{FB4}| < 0,008$

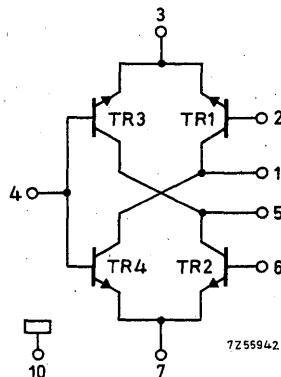
PACKAGE OUTLINE

TO-74 (reduced height)

Dimensions in mm



CIRCUIT DIAGRAM

**RATINGS** Limiting values in accordance with the Absolute Maximum System (IEC 134)Voltages (each transistor)

Collector-emitter voltage (open base)	V_{CEO}	max.	17,5	V
Emitter-base voltage (open collector)	V_{EBO}	max.	6,2	V
Collector-substrate voltage	V_{CS}	max.	65	V

Currents (each transistor)

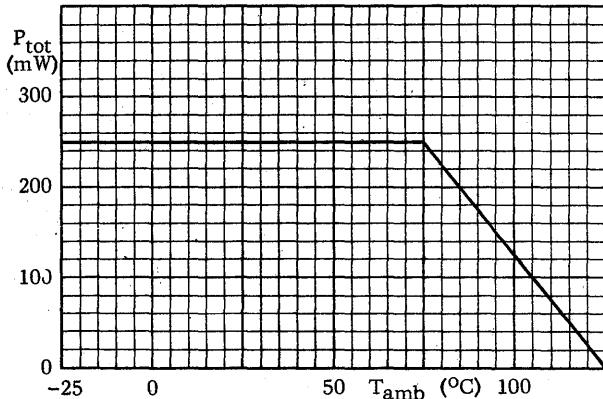
Collector current	I_C	max.	20	mA
→ Emitter cut-off current	I_{EBO}	max.	10	μ A

Power dissipation (4 transistors)

Total power dissipation	See curve below
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Temperatures

Storage temperature	T_{stg}	-55 to +125	°C
Operating ambient temperature	See curve below		



CHARACTERISTICS $T_{amb} = 25^{\circ}\text{C}$ unless otherwise specifiedCollector cut-off current $I_E = 0; V_{CB} = 5 \text{ V}$ I_{CBO} typ. < 5 100 nA nACollector-substrate leakage current $V_{CS} = 5 \text{ V}$ I_{CS} typ. < 5 100 nA nAEmitter cut-off current $I_C = 0; V_{EB} = 1 \text{ V}$ I_{EBO} typ. < 5 100 nA nABreakdown voltages $I_E = 0; I_C = 50 \mu\text{A}$ $V_{(BR)CBO}$ > 45 V $I_B = 0; I_C = 200 \mu\text{A}$ $V_{(BR)CEO}$ > 17,5 V $-I_S = 50 \mu\text{A}$ $V_{(BR)CS}$ > 65 V $I_C = 0; I_E = 10 \mu\text{A}$ $V_{(BR)EBO}$ > 6,2 VD.C. current gain $I_C = 150 \mu\text{A}; V_{CB} = 5 \text{ V}$ h_{FE} typ. > 35 90 $I_C = 10 \text{ mA}; V_{CB} = 5 \text{ V}$ h_{FE} typ. > 35 75Transition frequency at $f = 35 \text{ MHz}$ $I_C = 150 \mu\text{A}; V_{CB} = 5 \text{ V}$ f_T typ. > 140 MHz ← $I_C = 1 \text{ mA}; V_{CB} = 5 \text{ V}$ f_T typ. > 320 MHz ←Collector-base capacitance $V_{CB} = 5 \text{ V}; I_E = 0$ C_{cb} typ. 0,4 pFCollector-substrate capacitance $V_{CS} = 5 \text{ V}; I_E = 0$ C_{cs} typ. 2,8 pFBase-emitter voltage difference

between transistors TR1 and TR2 at

 $|V_{BE1}-V_{BE2}|$ typ. < 2 mV $-I_{E1} = -I_{E2} = 150 \mu\text{A}; V_{CB1} = V_{CB2} = 5 \text{ V}$ $|V_{BE1}-V_{BE2}|$ typ. < 5 mV

between transistors TR3 and TR4 at

 $|V_{BE3}-V_{BE4}|$ typ. < 2 mV $-I_{E3} = -I_{E4} = 150 \mu\text{A}; V_{CB3} = V_{CB4} = 5 \text{ V}$ $|V_{BE3}-V_{BE4}|$ typ. < 5 mVD.C. current gain differences

between transistors TR1 and TR2 at

 $|h_{FB1}-h_{FB2}|$ typ. < 0,002 $-I_{E1} = -I_{E2} = 150 \mu\text{A}; V_{CB1} = V_{CB2} = 5 \text{ V}$ $|h_{FB1}-h_{FB2}|$ typ. < 0,008

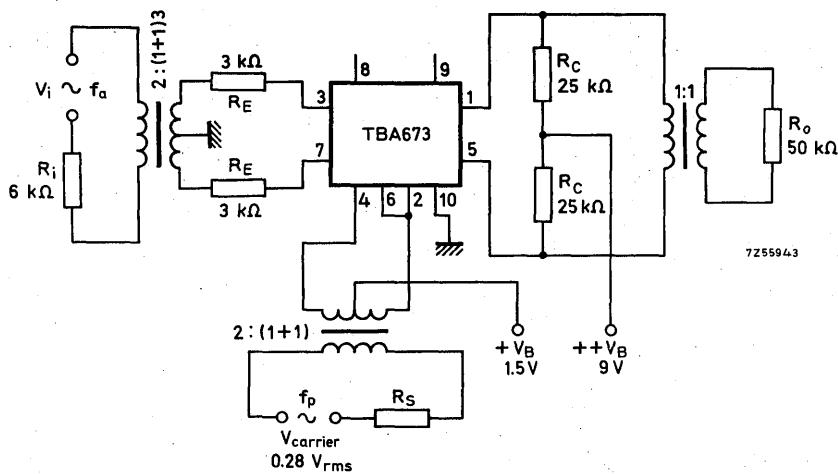
between transistors TR3 and TR4 at

 $|h_{FB3}-h_{FB4}|$ typ. < 0,002 $-I_{E3} = -I_{E4} = 150 \mu\text{A}; V_{CB3} = V_{CB4} = 5 \text{ V}$ $|h_{FB3}-h_{FB4}|$ typ. < 0,008

TBA673

APPLICATION INFORMATION

Telephony carriers ring modulator



Performance at $T_{amb} = 25^{\circ}\text{C}$

Conversion gain at $f_a = 1 \text{ kHz}$

$$V_i = 0, 4 \text{ V}; f_p = 34 \text{ kHz}$$

Carrier leakage power in R_o at $f_p = 34 \text{ kHz}$

G_C	typ.	-0, 75	dB
P_{oc}	typ.	3	nW